

## Thermal RC network (Foster)

## SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Rth(j-mb)	thermal resistance from junction to mounting base		-	-	0.64	K/W
	Cth <sub>1</sub>	1.572E-04 F		Д		
	Cth <sub>2</sub>	1.124E-03 F		<b>_</b>	tj	
	Cth <sub>3</sub>	8.462E-04 F				
	$Cth_4$	3.272E-03 F			$\begin{bmatrix} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$	
	Cth <sub>5</sub>	1.019E-02 F				
	Cth <sub>6</sub>	2.118E-02 F				
	Cth <sub>7</sub>	5.698E-01 F		- Г	<b>└ •</b> _ ]	
	Cth <sub>8</sub>	1.813E+02 F			$\int Rth_2 \stackrel{\bullet}{=} Cth_2$	2
	Rth₁	5.654E-04 Ω				
	Rth <sub>2</sub>	1.114E-03 Ω		Г		
	Rth <sub>3</sub>	1.315E-02 Ω			Rth3 🛨 Cth3	5
	Rth <sub>4</sub>	3.159E-02 Ω			┎┷╋┷┓┓	
	Rth₅	1.138E-01 Ω			<b>_</b>	
	Rth <sub>6</sub>	3.999E-01 Ω				I.
	Rth <sub>7</sub>	9.381E-02 Ω			<b></b>	r
	Rth <sub>8</sub>	1.005Ε-03 Ω	(	(P)		
						5
						5
						,
Part:	BUK753R1-40E					
Date:	17/4/2013					5
lodel Rth	0.65 K/W					
				$\overline{\mathbf{h}}$	t <sub>amb</sub>	
				v	001aal768	}

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